Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

**.037”**

**.037”**

**ANODE**

**.018 X .018”**

**Top Material: Al**

**Backside Material: Au**

**Bond Pad Size = .018 x .018”**

**Backside Potential: CATHODE**

**APPROVED BY: DK DIE SIZE .037” X .037” DATE: 9/1/21**

**MFG: CDI/MICROSEMI THICKNESS .016” P/N: 1N5301**

**DG 10.1.2**

#### Rev B, 7/1